

# PARLITE® UV GLUE AND UV ADHESIVE FOR ELECTRONIC ASSEMBLY

UV

Grade	Substrates	Viscosity @ 25° C	Shore Hardness	Elongation	Cure Mechanism	Tensile Strength	Application
4710	Metals, Plastics, Ferrite	17,000 - 20,000	45D	90%	UV, Visible or Heat	1,000 psi	High viscosity encapsulant for precision application to specific electronic assembly areas, glob top application.
4725	Metals, Ferrite, Plastics	600 - 800	55D	72%	UV, Visible or Heat	750 psi	Specifically designed for potting. Bonds with slight adhesion: for connectors, thermal switches, temper proofing.
4750	Metals, Ceramic, Glass-filled epoxy	150 - 200	85D	12%	UV, Visible and Heat	500 psi	Tough, glossy conformal coating with excellent adhesion to wide variety of boards and masks. Fast cure.
4760	Plastics, Glass, Metals	40,000 - 60,000	52D	48%	UV, Visible	1,200 psi	Potting, Encapsulating, bonding of electronic parts.